



Vincotech

flowDUAL E1	1200 V / 50 A
Topology features <ul style="list-style-type: none">• Common emitter point Half Bridge• Temperature sensor	flow E1 12 mm housing
Component features <ul style="list-style-type: none">• Easy paralleling• Low turn-off losses• Low collector-emitter saturation voltage• Positive temperature coefficient• Short tail current• Switching optimized for EMC	
Housing features <ul style="list-style-type: none">• Base isolation: Al₂O₃• Convex shaped substrate for superior thermal contact• Compact housing• CT1600 housing material• Thermo-mechanical push-and-pull force relief• Press-fit pin• Reliable cold welding connection	
Target applications <ul style="list-style-type: none">• Embedded Drives• General Purpose Drives• Industrial Drives	Schematic
Types <ul style="list-style-type: none">• 10-EZ122PC050M7-PL37F78T	



Vincotech

Maximum Ratings

$T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
AC Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current (DC current)	I_C	$T_j = T_{jmax}$ $T_s = 80^\circ\text{C}$	60	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	100	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80^\circ\text{C}$	124	W
Gate-emitter voltage	V_{GES}		± 20	V
Short circuit ratings	t_{SC}	$V_{GE} = 15\text{ V}$, $V_{CC} = 800\text{ V}$ $T_j = 150^\circ\text{C}$	9,5	μs
Maximum junction temperature	T_{jmax}		175	$^\circ\text{C}$

AC Diode

Peak repetitive reverse voltage	V_{RRM}		1200	V
Forward current (DC current)	I_F	$T_j = T_{jmax}$ $T_s = 80^\circ\text{C}$	46	A
Repetitive peak forward current	I_{FRM}	t_p limited by T_{jmax}	100	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ $T_s = 80^\circ\text{C}$	81	W
Maximum junction temperature	T_{jmax}		175	$^\circ\text{C}$

Module Properties

Thermal Properties

Storage temperature	T_{stg}		-40...+125	$^\circ\text{C}$
Operation temperature under switching condition	T_{jop}		-40...+($T_{jmax} - 25$)	$^\circ\text{C}$

Isolation Properties

Isolation voltage	V_{isol}	DC Test Voltage*	$t_p = 2\text{ s}$	6000	V
Creepage distance				>12,7	mm
Clearance				8,89	mm
Comparative Tracking Index	CTI			≥ 600	

*100 % tested in production



Vincotech

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V]	V_{GS} [V]	V_{CE} [V]	I_C [A]	T_j [°C]	Min	Typ	Max	

AC Switch

Static

Gate-emitter threshold voltage	$V_{GE(\text{th})}$			10	0,005	25	5,4	6	6,6	V
Collector-emitter saturation voltage	$V_{CE(\text{sat})}$		15		50	25 125 150		1,55 1,77 1,83	1,9 ⁽¹⁾	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			0,09	mA
Gate-emitter leakage current	I_{GES}		20	0		25			0,5	µA
Internal gate resistance	r_g							None		Ω
Input capacitance	C_{res}		0	10	25		10000		pF	
Output capacitance	C_{oes}									
Reverse transfer capacitance	C_{res}									
Gate charge	Q_g	$V_{CC} = 600$ V	0/15		50	25		380		nC

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{\text{paste}} = 3,4$ W/mK (PSX)						0,77		K/W
--	---------------	--	--	--	--	--	--	------	--	-----

Dynamic⁽³⁾

Turn-on delay time	$t_{d(on)}$	$R_{gon} = 8 \Omega$ $R_{goff} = 8 \Omega$	± 15	600	50	25		169,67		
Rise time	t_r					125		167,73		ns
						150		166,23		
Turn-off delay time	$t_{d(off)}$					25		41,88		
						125		42,96		
Fall time	t_f					150		44,35		ns
Turn-on energy (per pulse)	E_{on}					25		178,83		
		$Q_{tFWD}=4,29 \mu\text{C}$ $Q_{tFWD}=6,88 \mu\text{C}$ $Q_{tFWD}=7,76 \mu\text{C}$				125		206,75		
						150		213,27		ns
Turn-off energy (per pulse)	E_{off}					25		86,94		
						125		116,65		
						150		122,12		ns
						25		4,09		
						125		5,24		mWs
						150		5,56		
						25		3,62		
						125		5,02		mWs
						150		5,36		



Vincotech

Characteristic Values

Parameter	Symbol	Conditions						Values			Unit
		V_{GE} [V]	V_{GS} [V]	V_{CE} [V]	V_{DS} [V]	I_C [A]	I_D [A]	T_j [°C]	Min	Typ	Max

AC Diode

Static

Forward voltage	V_F				50	25 125 150		1,66 1,78 1,79	2,1 ⁽¹⁾	V
Reverse leakage current	I_R	$V_r = 1200$ V			25			40	μ A	

Thermal

Thermal resistance junction to sink ⁽²⁾	$R_{th(j-s)}$	$\lambda_{paste} = 3,4$ W/mK (PSX)						1,18		K/W
--	---------------	---------------------------------------	--	--	--	--	--	------	--	-----

Dynamic⁽³⁾

Peak recovery current	I_{RM}	$di/dt=1081$ A/ μ s $di/dt=842$ A/ μ s $di/dt=927$ A/ μ s	± 15	600	50	25 125 150		32,43 34,78 35,94		A
Reverse recovery time	t_{rr}					25 125 150		319,46 458,54 502,29		ns
Recovered charge	Q_r					25 125 150		4,29 6,88 7,76		μ C
Reverse recovered energy	E_{rec}					25 125 150		1,46 2,48 2,83		mWs
Peak rate of fall of recovery current	$(di_{rr}/dt)_{max}$					25 125 150		355,16 177,19 151,97		A/ μ s



Vincotech

Characteristic Values

Parameter	Symbol	Conditions					Values			Unit
		V_{GE} [V]	V_{GS} [V]	V_{CE} [V]	V_{DS} [V]	I_C [A]	T_j [°C]	Min	Typ	Max

Thermistor

Static

Rated resistance	R					25		5		kΩ
Deviation of R100	$A_{R/R}$	$R_{100} = 499 \Omega$				100	3,2		3,3	%
Power dissipation	P					25		130		mW
Power dissipation constant	d					25		1,3		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %						3380		K
Vincotech Thermistor Reference									V	

(1) Value at chip level

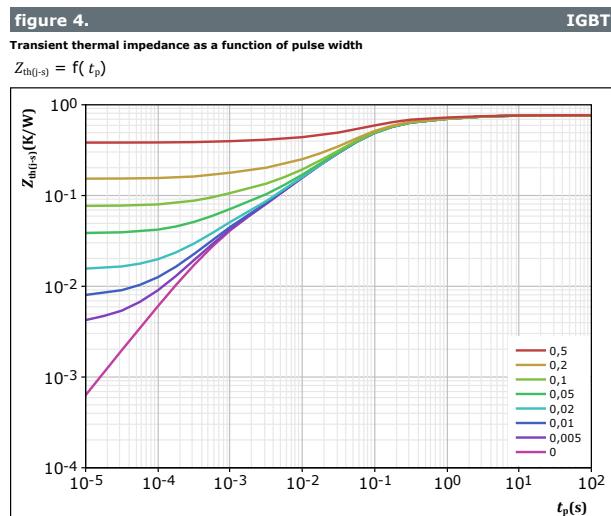
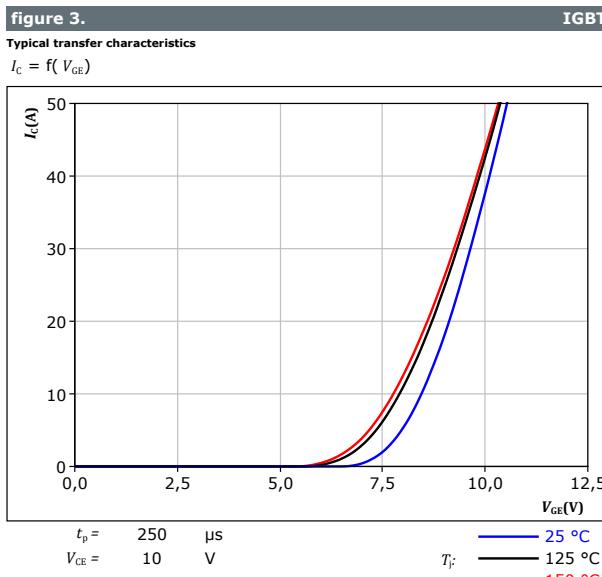
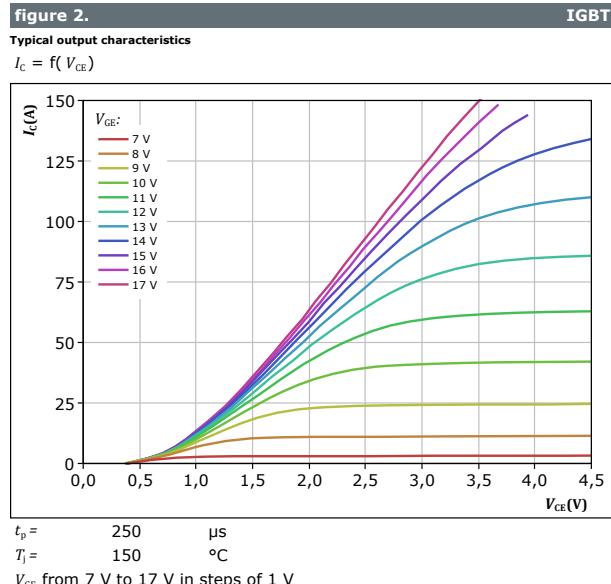
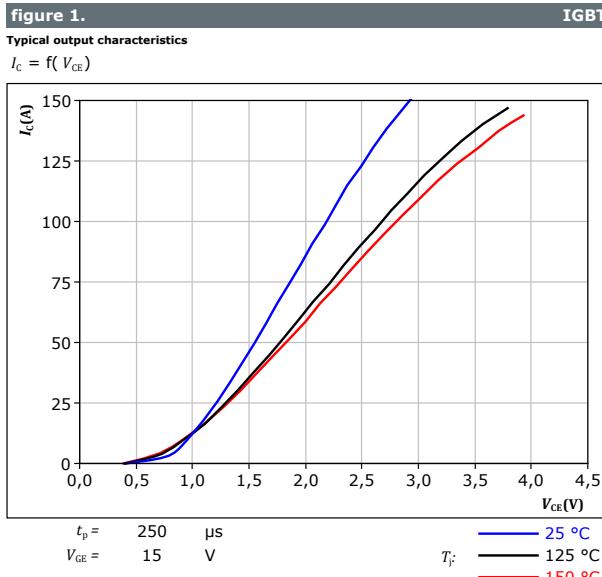
(2) Only valid with pre-applied Vincotech thermal interface material.

(3) The dynamic characterization was measured in a normal half-bridge configuration, which combines two 10-EZ122PC050M7-PL37F78T modules. Please consider, that the commutation loop in this configuration takes place between both modules.



Vincotech

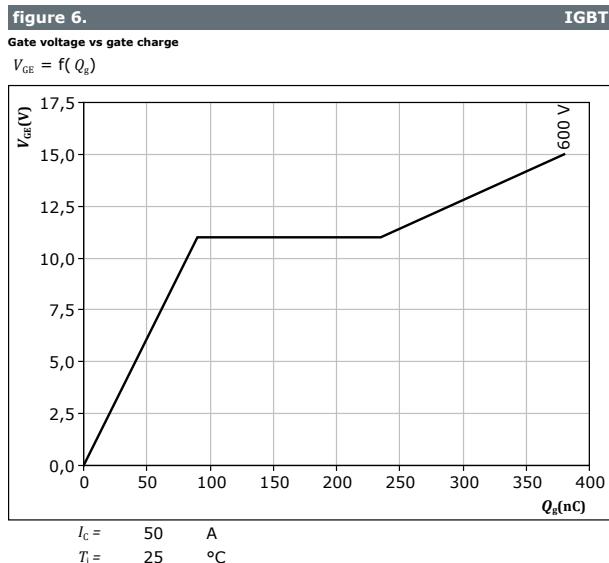
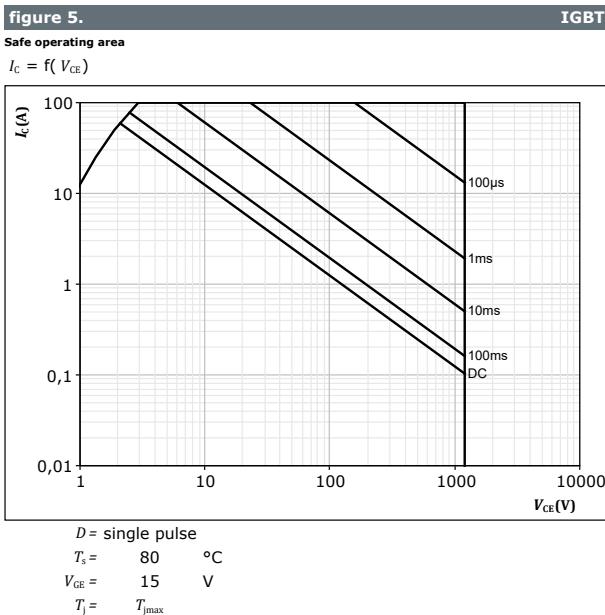
AC Switch Characteristics





Vincotech

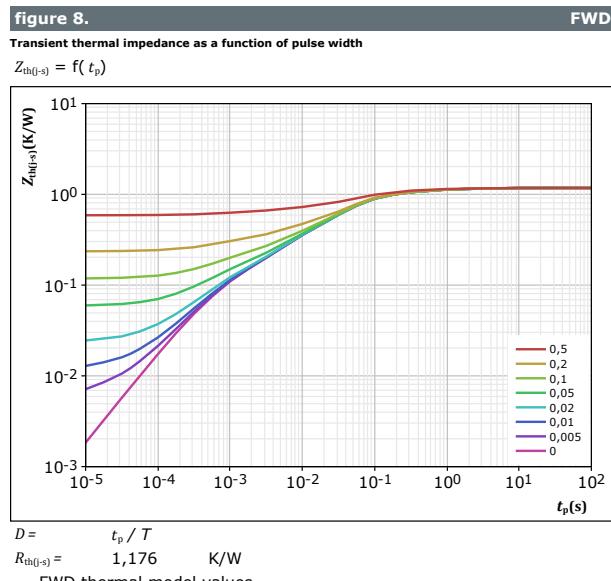
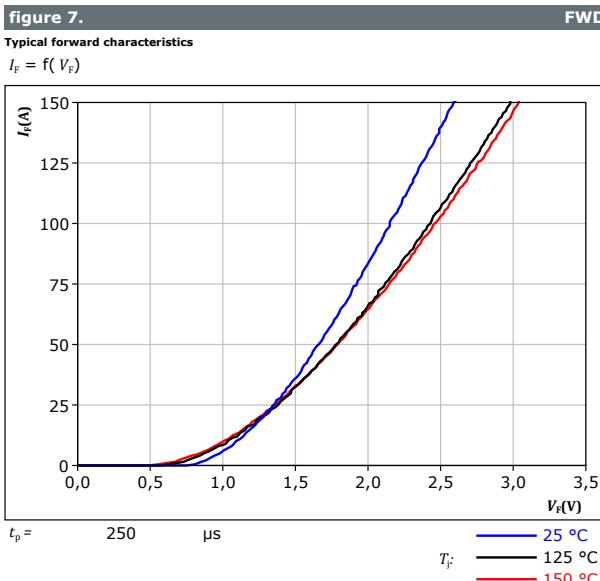
AC Switch Characteristics





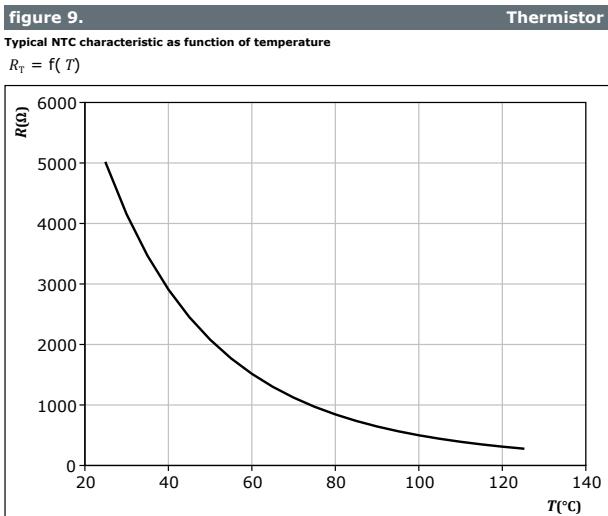
Vincotech

AC Diode Characteristics





Thermistor Characteristics





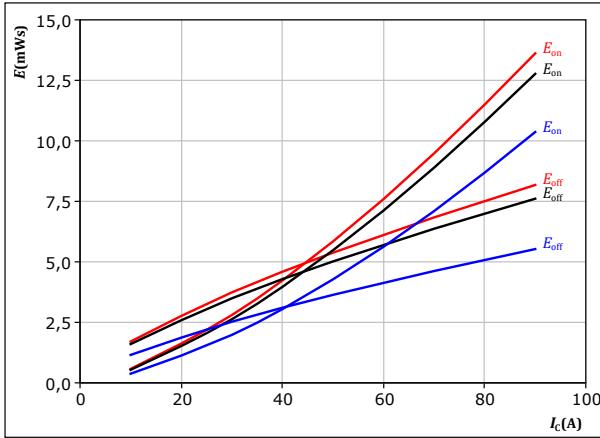
Vincotech

AC Switching Characteristics

figure 10. IGBT

Typical switching energy losses as a function of collector current

$$E = f(I_C)$$



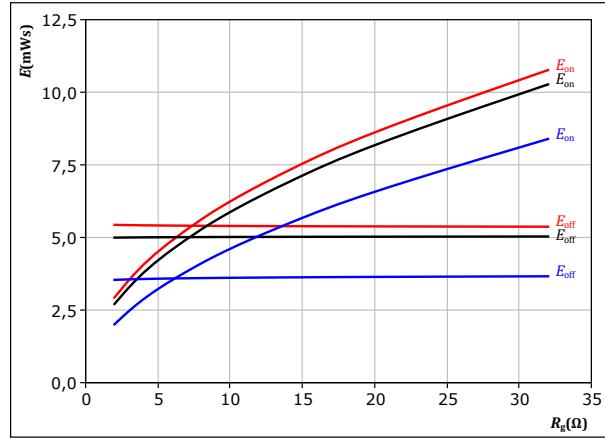
With an inductive load at

$V_{CE} =$	600	V
$V_{GE} =$	± 15	V
$R_{gon} =$	8	Ω
$R_{goff} =$	8	Ω

figure 11. IGBT

Typical switching energy losses as a function of IGBT turn on gate resistor

$$E = f(R_g)$$



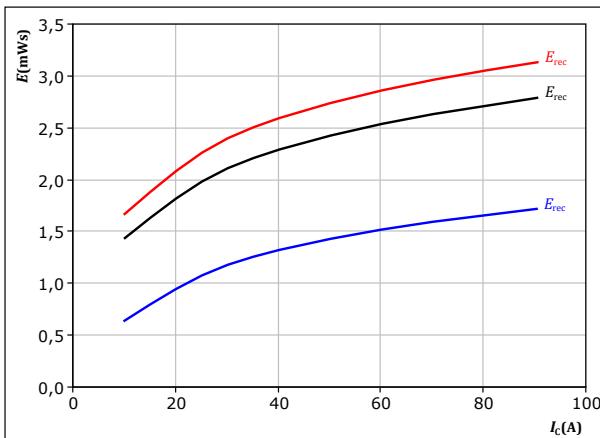
With an inductive load at

$V_{CE} =$	600	V
$V_{GE} =$	± 15	V
$I_C =$	50	A

figure 12. FWD

Typical reverse recovered energy loss as a function of collector current

$$E_{rec} = f(I_C)$$



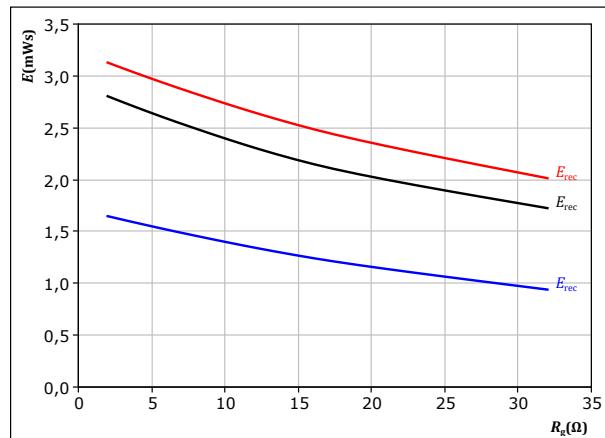
With an inductive load at

$V_{CE} =$	600	V
$V_{GE} =$	± 15	V
$R_{gon} =$	8	Ω

figure 13. FWD

Typical reverse recovered energy loss as a function of IGBT turn on gate resistor

$$E_{rec} = f(R_g)$$



With an inductive load at

$V_{CE} =$	600	V
$V_{GE} =$	± 15	V
$I_C =$	50	A

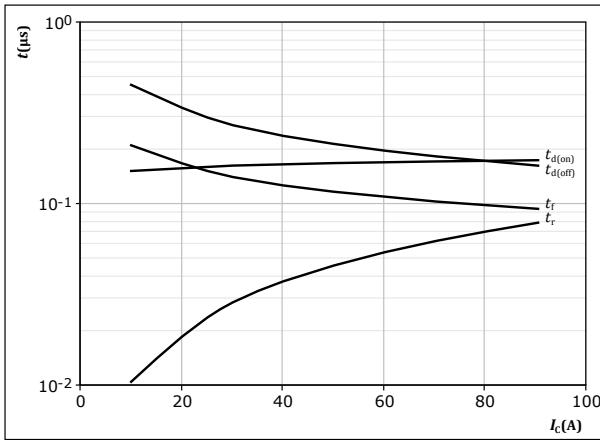


Vincotech

AC Switching Characteristics

figure 14. IGBT

Typical switching times as a function of collector current
 $t = f(I_C)$

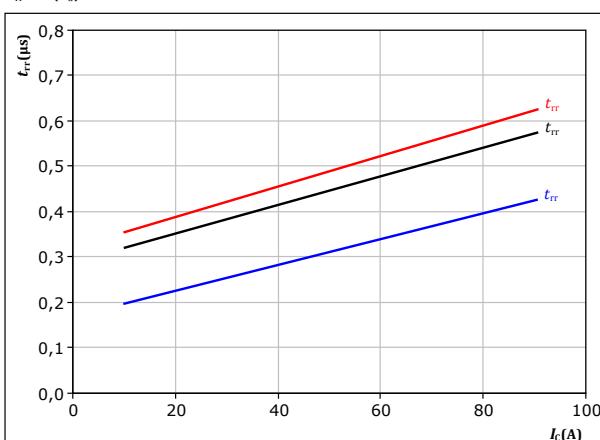


With an inductive load at

$T_j = 150^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \Omega$
 $R_{goff} = 8 \Omega$

figure 16. FWD

Typical reverse recovery time as a function of collector current
 $t_{rr} = f(I_C)$

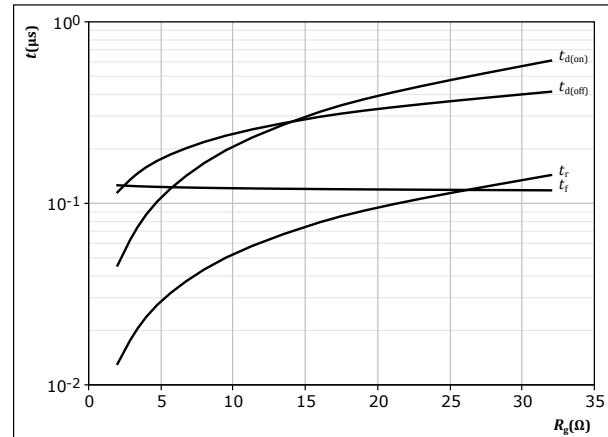


With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \Omega$

figure 15. IGBT

Typical switching times as a function of IGBT turn on gate resistor
 $t = f(R_g)$

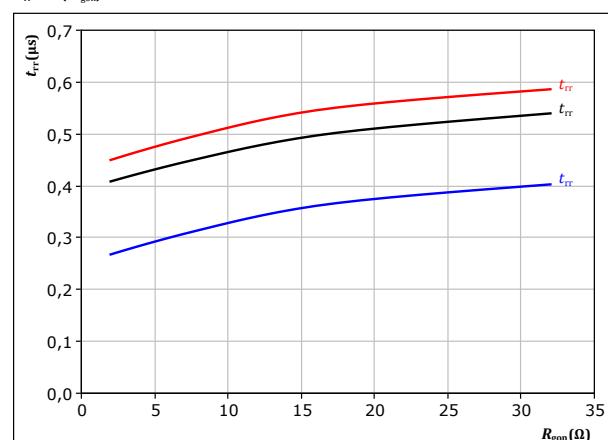


With an inductive load at

$T_j = 150^\circ\text{C}$
 $V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 50 \text{ A}$

figure 17. FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor
 $t_{rr} = f(R_{gon})$



With an inductive load at

$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_C = 50 \text{ A}$



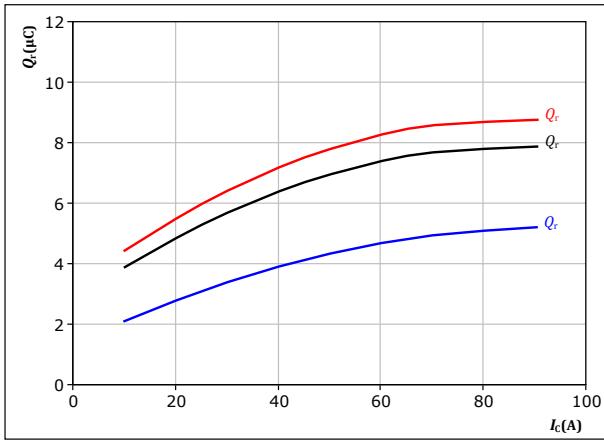
Vincotech

AC Switching Characteristics

figure 18.

Typical recovered charge as a function of collector current

$$Q_r = f(I_c)$$



FWD

figure 20.

Typical peak reverse recovery current as a function of collector current

$$I_{RM} = f(I_c)$$

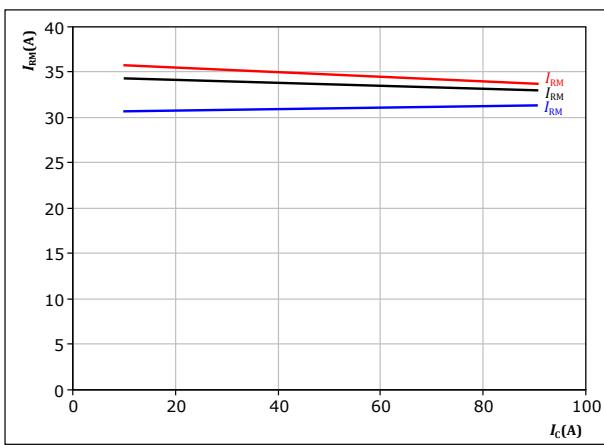
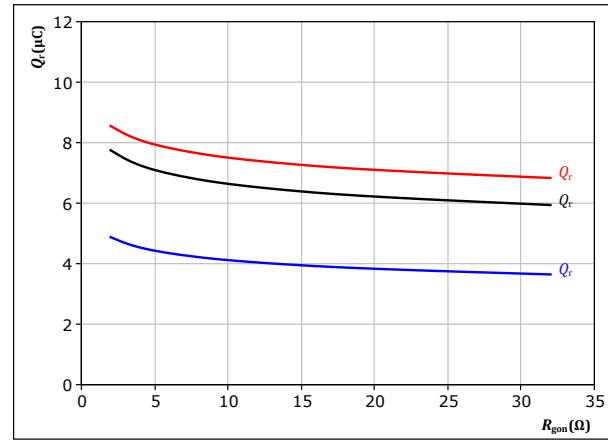


figure 19.

Typical recovered charge as a function of IGBT turn on gate resistor

$$Q_r = f(R_{gon})$$

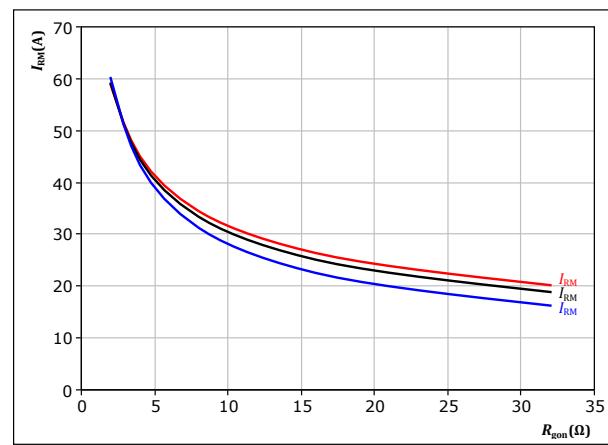


FWD

figure 21.

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$$I_{RM} = f(R_{gon})$$





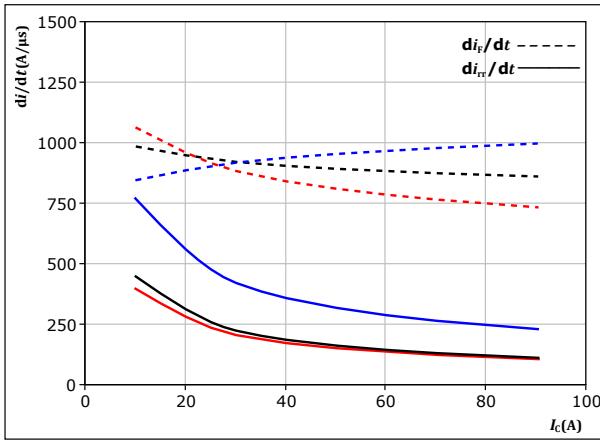
Vincotech

AC Switching Characteristics

figure 22. FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$di_f/dt, di_{rr}/dt = f(I_c)$



With an inductive load at

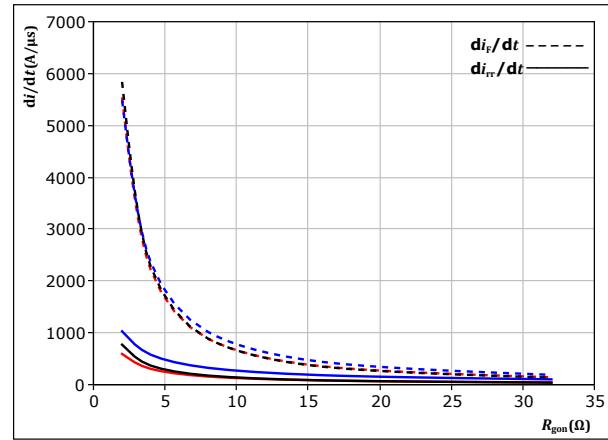
$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $R_{gon} = 8 \Omega$

$T_j = 25 \text{ }^\circ\text{C}$ ——— 125 °C
— 150 °C

figure 23. FWD

Typical rate of fall of forward and reverse recovery current as a function of turn on gate resistor

$di_f/dt, di_{rr}/dt = f(R_{gon})$



With an inductive load at

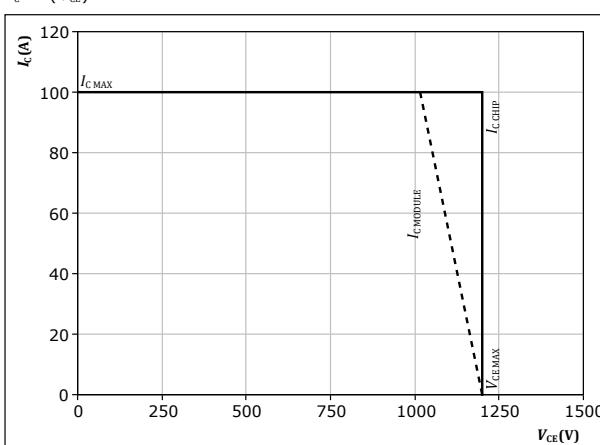
$V_{CE} = 600 \text{ V}$
 $V_{GE} = \pm 15 \text{ V}$
 $I_c = 50 \text{ A}$

$T_j = 25 \text{ }^\circ\text{C}$ ——— 125 °C
— 150 °C

figure 24. IGBT

Reverse bias safe operating area

$I_c = f(V_{CE})$



At $T_j = 150 \text{ }^\circ\text{C}$
 $R_{gon} = 8 \Omega$
 $R_{goff} = 8 \Omega$



Vincotech

AC Switching Definitions

figure 25. IGBT

Turn-off Switching Waveforms & definition of t_{doff} , t_{Eoff} (t_{Eoff} = integrating time for E_{off})

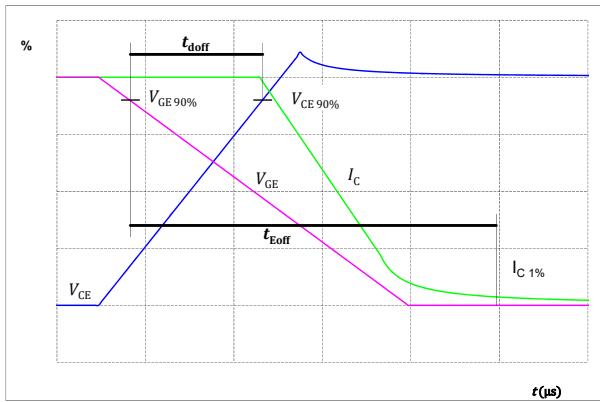


figure 26. IGBT

Turn-on Switching Waveforms & definition of t_{don} , t_{Eon} (t_{Eon} = integrating time for E_{on})

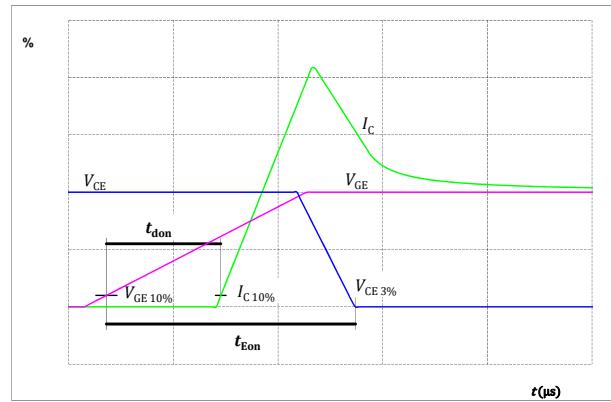


figure 27. IGBT

Turn-off Switching Waveforms & definition of t_f

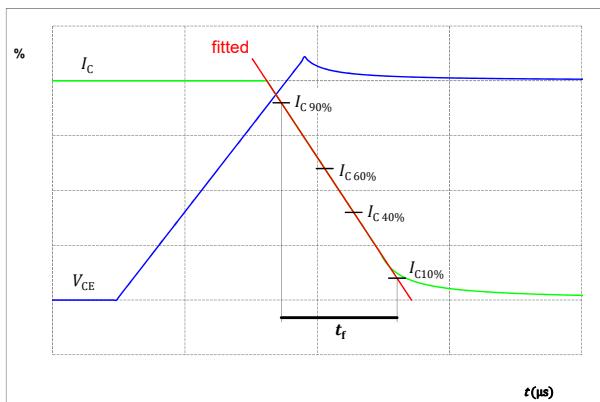
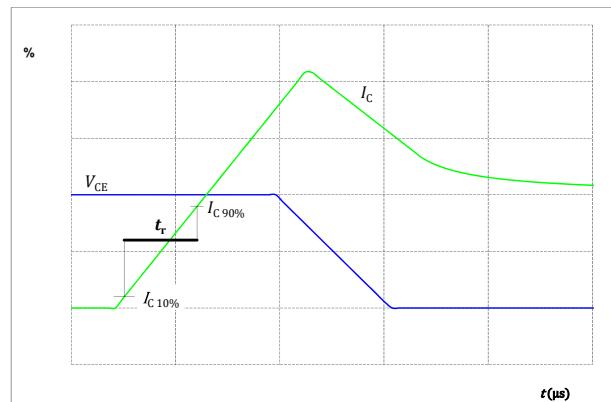


figure 28. IGBT

Turn-on Switching Waveforms & definition of t_r





Vincotech

AC Switching Definitions

figure 29.

Turn-off Switching Waveforms & definition of t_{tr}

FWD

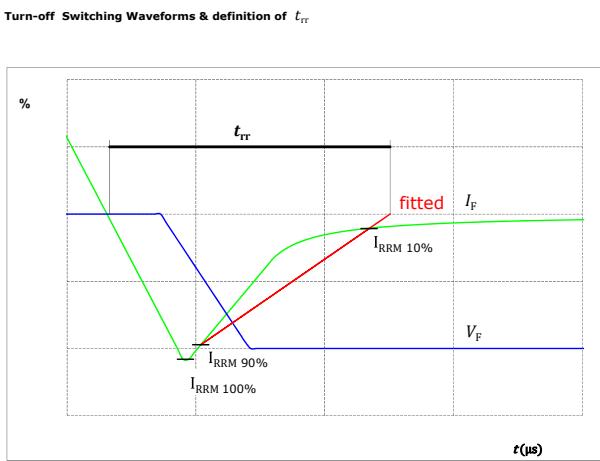
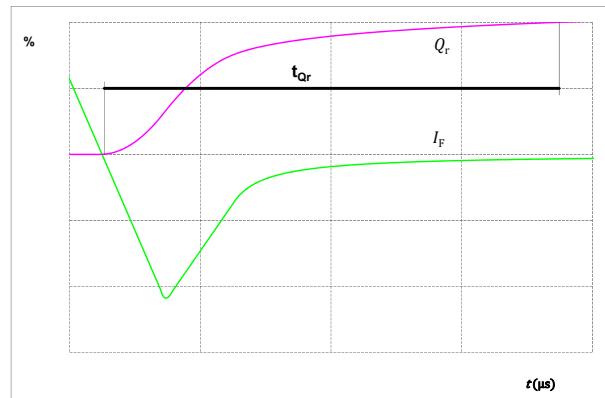


figure 30.

Turn-on Switching Waveforms & definition of t_{qr} (t_{qr} = integrating time for Q_r)

FWD





10-EZ122PC050M7-PL37F78T

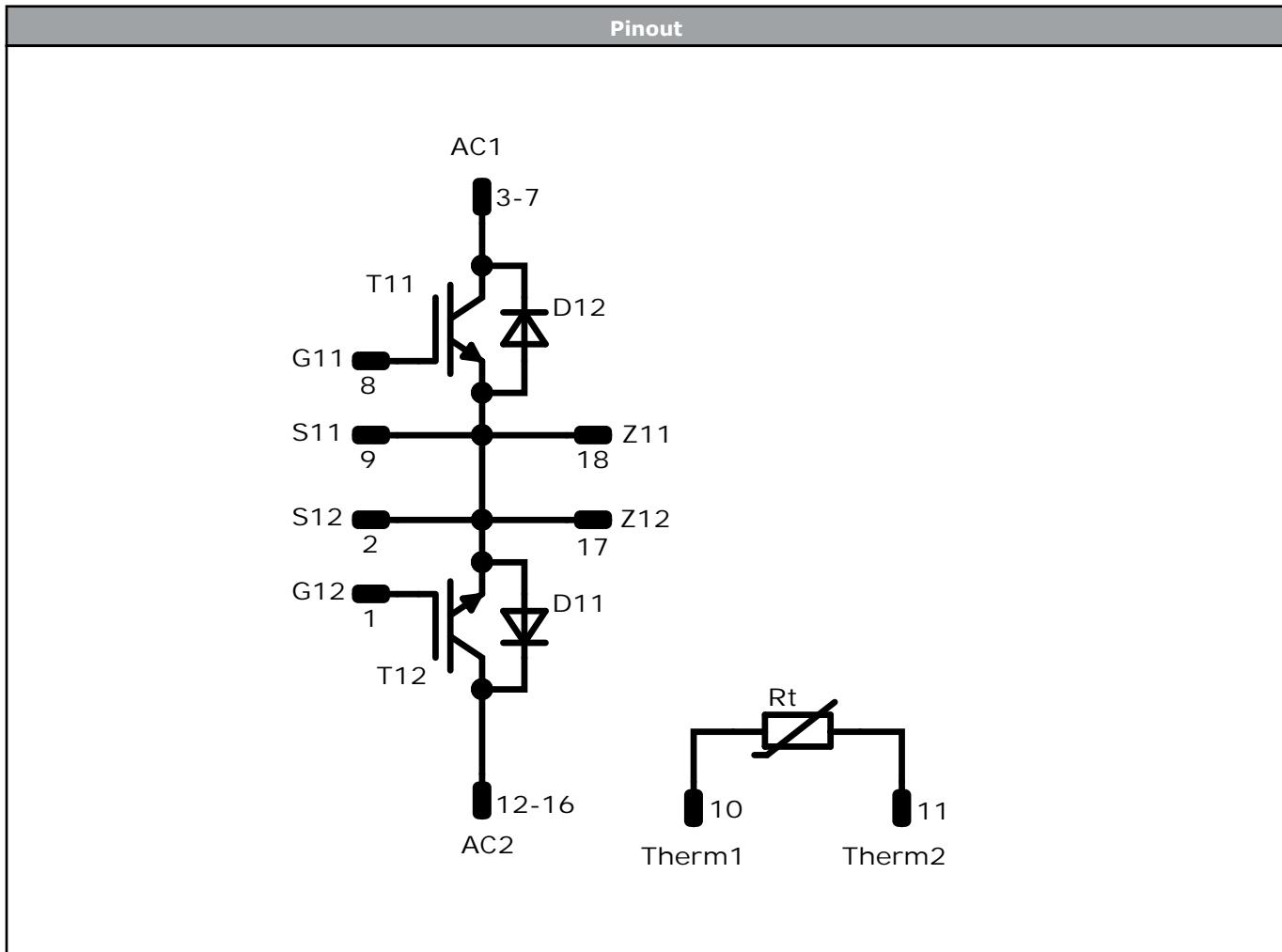
datasheet

Vincotech

Ordering Code																																																																																	
Version			Ordering Code																																																																														
Without thermal paste			10-EZ122PC050M7-PL37F78T																																																																														
With thermal paste (3,4 W/mK, PSX-P7)			10-EZ122PC050M7-PL37F78T-3/																																																																														
Marking																																																																																	
	Text	Name NN-NNNNNNNNNNNNN TTTTTTVVV VIN LLLLL SSSS	Date code WWYY	UL & VIN UL VIN	Lot LLLLL																																																																												
	Datamatrix	Type&Ver TTTTTTVV Lot number LLLLL	Serial SSSS	Date code WWYY	Serial SSSS																																																																												
Outline																																																																																	
<table border="1"><caption>Pin table [mm]</caption><thead><tr><th>Pin</th><th>X</th><th>Y</th><th>Function</th></tr></thead><tbody><tr><td>1</td><td>32</td><td>0</td><td>G12</td></tr><tr><td>2</td><td>28,8</td><td>0</td><td>S12</td></tr><tr><td>3</td><td>0</td><td>6,4</td><td>AC1</td></tr><tr><td>4</td><td>0</td><td>9,6</td><td>AC1</td></tr><tr><td>5</td><td>0</td><td>12,8</td><td>AC1</td></tr><tr><td>6</td><td>0</td><td>16</td><td>AC1</td></tr><tr><td>7</td><td>0</td><td>19,2</td><td>AC1</td></tr><tr><td>8</td><td>0</td><td>25,6</td><td>G11</td></tr><tr><td>9</td><td>3,2</td><td>25,6</td><td>S11</td></tr><tr><td>10</td><td>28,8</td><td>25,6</td><td>Therm1</td></tr><tr><td>11</td><td>32</td><td>25,6</td><td>Therm2</td></tr><tr><td>12</td><td>32</td><td>19,2</td><td>AC2</td></tr><tr><td>13</td><td>32</td><td>16</td><td>AC2</td></tr><tr><td>14</td><td>32</td><td>12,8</td><td>AC2</td></tr><tr><td>15</td><td>32</td><td>9,6</td><td>AC2</td></tr><tr><td>16</td><td>32</td><td>6,4</td><td>AC2</td></tr><tr><td>17</td><td>25,6</td><td>0</td><td>Z12</td></tr><tr><td>18</td><td>6,4</td><td>25,6</td><td>Z11</td></tr></tbody></table>	Pin	X	Y	Function	1	32	0	G12	2	28,8	0	S12	3	0	6,4	AC1	4	0	9,6	AC1	5	0	12,8	AC1	6	0	16	AC1	7	0	19,2	AC1	8	0	25,6	G11	9	3,2	25,6	S11	10	28,8	25,6	Therm1	11	32	25,6	Therm2	12	32	19,2	AC2	13	32	16	AC2	14	32	12,8	AC2	15	32	9,6	AC2	16	32	6,4	AC2	17	25,6	0	Z12	18	6,4	25,6	Z11	<p>center of gage-tilt pin test pin head type: TT, R5 plated through-hole Ø1.00 ±0.05 /-0.06 for further PCB design rules refer to the latest handling instruction</p> <p>Tolerance of pin positions: ±0.1mm at the end of pins Dimension of coordinate axis is only offset without tolerance</p>				
Pin	X	Y	Function																																																																														
1	32	0	G12																																																																														
2	28,8	0	S12																																																																														
3	0	6,4	AC1																																																																														
4	0	9,6	AC1																																																																														
5	0	12,8	AC1																																																																														
6	0	16	AC1																																																																														
7	0	19,2	AC1																																																																														
8	0	25,6	G11																																																																														
9	3,2	25,6	S11																																																																														
10	28,8	25,6	Therm1																																																																														
11	32	25,6	Therm2																																																																														
12	32	19,2	AC2																																																																														
13	32	16	AC2																																																																														
14	32	12,8	AC2																																																																														
15	32	9,6	AC2																																																																														
16	32	6,4	AC2																																																																														
17	25,6	0	Z12																																																																														
18	6,4	25,6	Z11																																																																														



Vincotech



Identification					
ID	Component	Voltage	Current	Function	Comment
T11, T12	IGBT	1200 V	50 A	AC Switch	
D12, D11	FWD	1200 V	50 A	AC Diode	
Rt	Thermistor			Thermistor	



10-EZ122PC050M7-PL37F78T

datasheet

Vincotech

Packaging instruction				
Standard packaging quantity (SPQ) 100	>SPQ	Standard	<SPQ	Sample

Handling instruction				
Handling instructions for flow E1 packages see vincotech.com website.				

Package data				
Package data for flow E1 packages see vincotech.com website.				

Vincotech thermistor reference				
See Vincotech thermistor reference table at vincotech.com website.				

UL recognition and file number				
This device is UL 1557 recognized under E192116 up to a junction temperature under switching condition $T_{j,op}=175^{\circ}\text{C}$ and up to 3500VAC/1min isolation voltage. For more information see vincotech.com website.				

Document No.:	Date:	Modification:	Pages
10-EZ122PC050M7-PL37F78T-D1-14	12 Apr. 2024		

DISCLAIMER

The information, specifications, procedures, methods and recommendations herein (together "information") are presented by Vincotech to reader in good faith, are believed to be accurate and reliable, but may well be incomplete and/or not applicable to all conditions or situations that may exist or occur. Vincotech reserves the right to make any changes without further notice to any products to improve reliability, function or design. No representation, guarantee or warranty is made to reader as to the accuracy, reliability or completeness of said information or that the application or use of any of the same will avoid hazards, accidents, losses, damages or injury of any kind to persons or property or that the same will not infringe third parties rights or give desired results. It is reader's sole responsibility to test and determine the suitability of the information and the product for reader's intended use.

LIFE SUPPORT POLICY

Vincotech products are not authorised for use as critical components in life support devices or systems without the express written approval of Vincotech.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.
2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.